

Package 封装 :BGA (Flip-Chip), Lead-Free (Pb-free)
 Lead Free 无铅: Yes 是

有毒有害物质名称及含量的标识格式						
Table of hazardous substances' name and concentration						
均质材料	铅	镉	六价铬	汞	多溴联苯	多溴联苯醚
Homogeneous Material	Pb	Cd	Cr6+	Hg	PBB	PBDE
Heat Spreader 散热片	O	O	O	O	O	O
Substrate 基板	O	O	O	O	O	O
DA epoxy 贴胶	O	O	O	O	O	O
Die, 晶片	O	O	O	O	O	O
Solder ball 焊球	O	O	O	O	O	O
Stiffener Adhesive 补强件接着剂	O	O	O	O	O	O
Underfill 填充料	O	O	O	O	O	O
FC bump pad 反晶焊点接面	X*	O	O	O	O	O
Solder bump 焊点	X*	O	O	O	O	O

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O: Indicates that the concentration of the hazardous substance in all homogeneous materials in the parts is below the relevant threshold of the SJ/T11363-2006 standard.

O: 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006 标准规定的限量要求以下.

X: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard.

X: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求.

X*: Indicates that the concentration of the hazardous substance of at least one of all homogeneous materials in the parts is above the relevant threshold of the SJ/T11363-2006 standard, but it is exempted by EU ROHS.

X*: 示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006 标准规定的限量要求。但是可以被欧盟(EU ROHS)所豁免的。

Document Revision History	
Date and Document Version	Changes Made
March 2007 v1.1	Updated table to include the symbol explanation
March 2007 v1.0	Initial Release

